

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **04269895 A**

(43) Date of publication of application: **25.09.92**

(51) Int. Cl

H05K 3/34

(21) Application number: **03053132**

(71) Applicant: **KONDO KENJI**

(22) Date of filing: **26.02.91**

(72) Inventor: **KONDO KENJI**

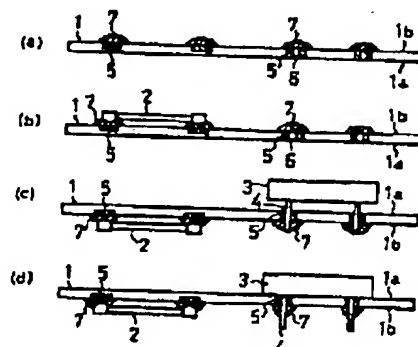
(54) REFLOW SOLDER METHOD FOR PRINTED BOARD

(57) Abstract:

PURPOSE: To obtain a method for simultaneously soldering a printed board temporarily adhered with a chip component having high heat resistant temperature and an electronic component with leads having a low heat resistant temperature at once in a heat atmosphere.

CONSTITUTION: After a printed board 1 is coated with solder paste 7, a chip component 2 is temporarily adhered, then inverted, an electronic component 3 with leads is inserted from a main surface 1a of the board 1 into a through hole 6 of the board 1, and then soldered in a reflow soldering machine 21 in which the surface 1a of the board 1 is in a low temperature heat atmosphere and the surface 1b side of the board 1 is in a high temperature heat atmosphere.

COPYRIGHT: (C)1992,JPO&Japio



BEST AVAILABLE COPY